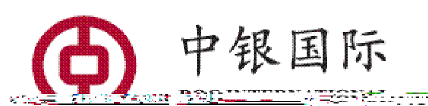
600584

99



200 39

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		2014
		STATS ChipPAC Ltd.
APS		ADVANPACK SOLUTIONS PTE LTD.
		2012 2013 2014 2015 1-4
		2013 2014 2015 1-4
		, 4 5 6 8 12 8
IDM		
FC		Flip-Chip
BUMPING		
WLCSP		Wafer level Chip size package

TSV		Through Silicon Via
SIP		Single In-line Package

16.188%

100%

100%

120 90% 11.72

/

33,023.52

2,817.71

100%

20 90% 14.14 /

33,023.52

33,023.52

2,335.47

48

50%

16.188% 2015 4

1.92% APS

3.812%

2014

	16.188%	1.92%	3.812%			
	33,023.52	3,838.50	7,608.83	44,470.85	1,090,230.47	4.08%
	33,023.52	3,838.50	7,608.83	44,470.85	376,385.09	11.82%
	23,254.92	2,758.18	5,476.14	31,489.24	642,827.33	4.90%

2015 4 30

33,023.52

36 6 20

6

6

36

/ 2014 143,655.27

22.35% 2014 17,229.40

82.53%

76.92% 6.892%

100%

98,457.00

2,817.71 11.72 /

2,335.47 14.14 /

	13,892.74	14.11%	19,045.92	18.38%
	84,564.26	85.89%	84,564.26	81.62%
	98,457.00	**100%**	**103,610.17**	**100%**

14.11%

18.38%

1

2

3

4

		2 / /

2015 4 7

2015 5 21

2015 5 19

1

2

6

3

2015 4 30 11,646.99

33,023.52 21,376.53 183.54%

2008 20

-0.4% 2009

2010

18-24

FC QFN FCOL FCOS WL-CSP

APS 20

2003 8 7 2023 8 7

8

APS

90%